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PATENT

IN THE UNITED STATES DESIGNATED OFFICE (DO/US)

<u>PCT/JP00/09133</u>	<u>22 December 2000</u>	<u>24 December 1999</u>
INTERNATIONAL APPLICATION NO.	INTERNATIONAL FILING DATE	PRIORITY DATE CLAIMED

TITLE OF INVENTION
HEAT SINK MATERIAL AND METHOD OF PRODUCING THE SAME

APPLICANT(S) FOR DO/US
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Elizabeth A. VanAntwerp

**SUBMISSION OF PROPOSED DRAWING AMENDMENT
FOR APPROVAL BY EXAMINER**

Sir:

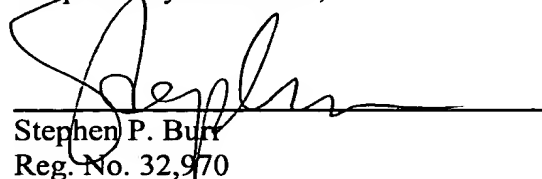
Attached please find

(check applicable items)

☒ a copy of the original drawings (Figs. 21 and 24) with red ink markings, showing the proposed changes to the drawings in this application, and

☒ if drawings are approved by the Examiner, we also enclose formal drawings for Figs. 21 and 24.

Respectfully submitted,


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August 13, 2001
Date

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FIG. 21 METAL IMPREGNATING METHOD IMPREGNATION PRESSURE COEFFICIENT OF THERMAL CONDUCTIVITY WATER RESISTANCE

SAMPLE	SIZE (mm)	METAL	ADDITIVE ELEMENT	AMOUNT OF ADDITION (wt%)	IMPREGNATING METHOD	(MPa)	(W/mK)	COEFFICIENT OF THERMAL EXPANSION ($\times 10^{-6}/K$)		BENDING STRENGTH (MPa)		COMPRESSIVE STRENGTH (MPa)		EFFECT
								SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS	
n1-1	20×60×60	Al	NONE	NONE	PRESS	26.7	156	5.5	6.0	31.4	51.9	46.1	51.0	△
n1-4	20×120×190	Al	NONE	NONE	PRESS	60.0	185	5.5	6.5					△
n1-2	20×60×60	Cu	NONE	NONE	PRESS	26.7	150	3.8	4.5	26.5	39.2			◎
n1-3	20×120×190	Cu	NONE	NONE	PRESS	26.7	147	3.9	4.5	26.5	39.2			◎
n2-1	20×60×60	Cu	Te	0.500	PRESS	26.7	190	3.8	4.5	26.5	39.2			◎
n3-1	20×60×60	Cu	Be	1.000	PRESS	26.7	183	3.8	4.5	38.2	62.7			△
n3-2	20×120×190	Cu	Be	1.000	PRESS	156.1	189	4.0	4.6	37.2	61.7			△
n3-3	20×60×60	Cu	Cr	0.500	PRESS	26.7	180	3.8	4.5	36.3	59.8			△
n3-4	20×60×60	Cu	Mn	0.500	PRESS	26.7	176	3.8	4.5	34.3	55.9			△
n3-5	20×60×60	Cu	Nb	0.050	PRESS	156.1	198	3.8	4.5	35.3	57.8	42.1	48.0	△
n3-6	20×120×190	Cu	Nb	0.050	PRESS	26.7	167	3.8	4.5	35.3	57.8			△
n3-7	20×60×60	Cu	Zr	0.500	PRESS	26.7	158	3.8	4.5	34.3	56.8			△
n3-8	20×120×190	Cu	Nb	0.001	PRESS	43.3	182	4.5	3.0					△
n3-9	20×120×190	Cu	Nb	0.001	PRESS	60.0	182	4.0	3.0					△
n3-10	20×120×190	Cu	Nb	1.100	PRESS	60.0	196	4.0	3.5					△
n3-11	20×120×190	Cu	Be	1.900	PRESS	60.0	186	4.5	3.5					△
n3-12	20×120×190	Cu	Ni, Sn	9.4, 6.7	PRESS	60.0	190	343						△
n3-13	20×120×190	Cu	Ni, Si, P	1.0, 0.23, 0.04	PRESS	60.0	190	353						△
n3-14	20×120×190	Cu	Mn	4.180	PRESS	60.0	181	352						△
n3-15	20×120×190	Cu	Cr	2.870	PRESS	60.0	195	387						△
n3-16	20×120×190	Cu	Zr	4.490	PRESS	60.0	207	367						△
n3-17	20×120×190	Cu	Si	11.300	PRESS	26.7	157	333						△
n3-18	20×120×190	Cu	Si	10.900	PRESS	60.0	159	316						△
n3-19	20×120×190	Cu	Si	5.170	PRESS	153.0	165	343						△
n3-20	20×120×190	Cu	Si	5.300	PRESS	43.3	163	325						△
n5-1	20×60×60	Cu	NONE	NONE	GAS	26.7	170	320	4.5	26.5	39.2			◎
n7-1	20×120×190	Al	Be	2.000	PRESS	60.0	177	332	6.5			57.8	62.7	△
n7-2	20×120×190	Al	Si	5.000	PRESS	60.0	169	329	6.5			50.0	61.7	◎
n7-3	20×120×190	Al	Si	12.000	PRESS	60.0	181	327	6.5			56.8	68.6	◎

GENERATION OF
CARBIDE

COMBINED
ADDITION

GENERATION OF
CARBIDE

EXPANSION OF
SOLID-LIQUID
RANGE

NONE

GENERATION
OF CARBIDE

EXPANSION OF
SOLID-LIQUID
RANGE

FIG. 24

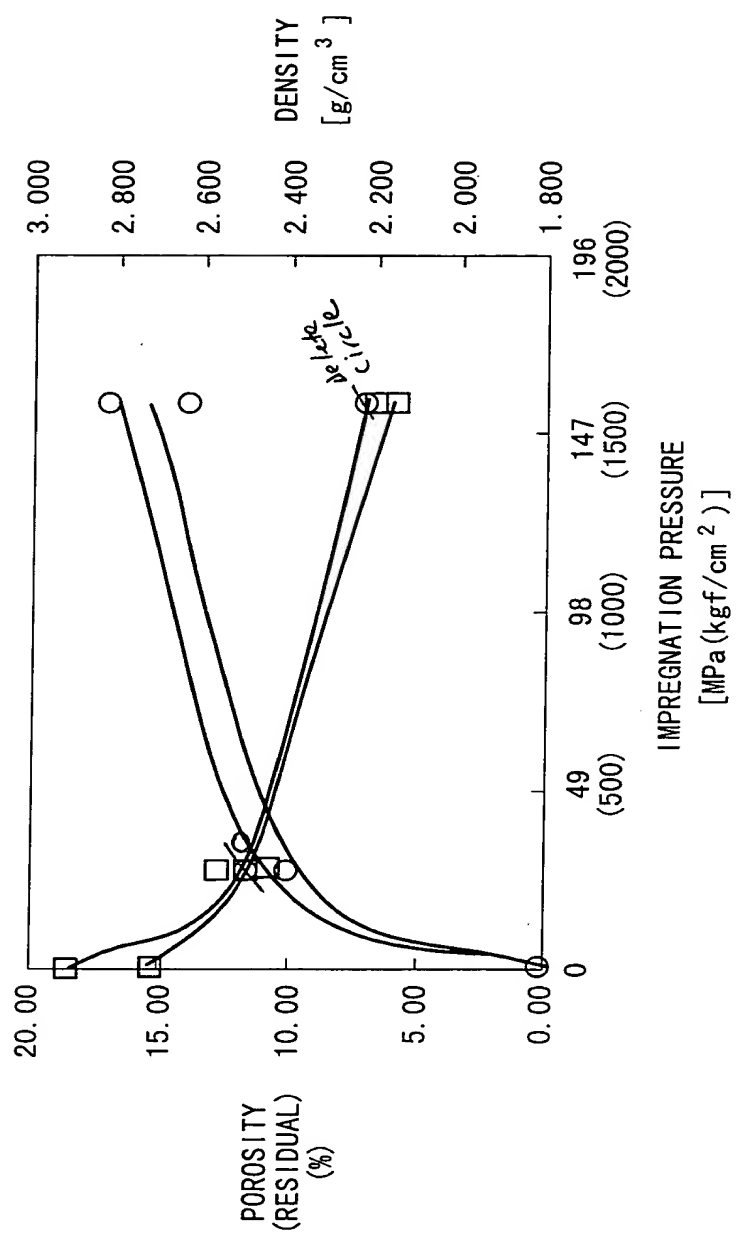


FIG. 21

SAMPLE	SIZE (mm)	METAL	IMPREGNATING METHOD		IMPREGNATION PRESSURE COEFFICIENT OF THERMAL CONDUCTIVITY		COEFFICIENT OF THERMAL EXPANSION ($\times 10^{-6}/K$)		BENDING STRENGTH (MPa)		COMpressive STRENGTH (MPa)		EFFECT	
		ADDITIVE ELEMENT	AMOUNT OF ADDITION (wt%)		(MPa)	(W/mK)	SUR-FACE	THICK-NESS	SUR-FACE	THICK-NESS	SUR-FACE	THICK-NESS		
n1-1	20×60×60	Al	NONE	PRESS	26.7	156	5.5	6.0	31.4	51.9	46.1	51.0	△	NONE
n1-4	20×120×190	Al	NONE	PRESS	60.0	185	5.5	6.5					△	NONE
n1-2	20×60×60	Cu	NONE	PRESS	26.7	150	3.8	4.5	26.5	39.2			◎	NONE
n1-3	20×120×190	Cu	NONE	PRESS	26.7	147	3.9	4.5	26.5	39.2			◎	NONE
n2-1	20×60×60	Te	0.500	PRESS	26.7	190	3.8	4.5	26.5	39.2			◎	WETTABILITY
n3-1	20×60×60	Be	1.000	PRESS	26.7	183	3.8	4.5	38.2	62.7			△	GENERATION OF CARBIDE
n3-2	20×120×190	Be	1.000	PRESS	156.1	189	4.0	4.6	37.2	61.7			△	
n3-3	20×60×60	Cr	0.500	PRESS	26.7	180	3.8	4.5	36.3	59.8			△	
n3-4	20×60×60	Mn	0.500	PRESS	26.7	176	3.8	4.5	34.3	55.9	42.1	48.0	△	
n3-5	20×60×60	Nb	0.050	PRESS	156.1	198	3.8	4.5	35.3	57.8			△	
n3-6	20×120×190	Nb	0.050	PRESS	26.7	167	3.8	4.5	35.3	57.8			△	
n3-7	20×60×60	Zr	0.500	PRESS	26.7	158	3.8	4.5	34.3	56.8			△	
n3-8	20×120×190	Nb	0.001	PRESS	43.3	182	4.5	3.0			40.2	51.9	△	
n3-9	20×120×190	Nb	0.001	PRESS	60.0	182	4.0	3.0			42.1	51.9	△	
n3-10	20×120×190	Nb	1.100	PRESS	60.0	196	4.0	2.5			51.0	58.8	△	
n3-11	20×120×190	Be	1.900	PRESS	60.0	186	4.5	3.5			57.8	64.7	△	COMBINED ADDITION
n3-12	20×120×190	Ni, Sn	9.4, 6.7	PRESS	60.0	190	343				51.9	51.0	◎	
n3-13	20×120×190	Ni, Si, P	1.0, 0.23, 0.04	PRESS	60.0	190	353				48.0	51.9	◎	
n3-14	20×120×190	Mn	4.180	PRESS	60.0	181	352				51.0	54.9	△	
n3-15	20×120×190	Cr	2.870	PRESS	60.0	195	387				48.0	51.9	△	EXPANSION OF SOLID-LIQUID RANGE
n3-16	20×120×190	Zr	4.490	PRESS	60.0	207	367				53.9	63.7	△	
n3-17	20×120×190	Si	11.300	PRESS	26.7	157	333				53.9	60.8	◎	
n3-18	20×120×190	Si	10.900	PRESS	60.0	159	316				56.8	68.6	◎	
n3-19	20×120×190	Si	5.170	PRESS	153.0	165	343				52.9	62.7	◎	NONE
n3-20	20×120×190	Si	5.300	PRESS	43.3	163	325				54.9	60.8	◎	
n5-1	20×60×60	Cu	NONE	GAS	26.7	170	320	4.5	26.5	39.2			◎	GENERATION OF CARBIDE
n7-1	20×120×190	Al	2.000	PRESS	60.0	177	332	6.5			57.8	62.7	△	EXPANSION OF SOLID-LIQUID RANGE
n7-2	20×120×190	Al	5.000	PRESS	60.0	169	329	6.5			50.0	61.7	◎	NONE
n7-3	20×120×190	Al	12.000	PRESS	60.0	181	327	6.5			56.8	68.6	◎	

FIG. 24

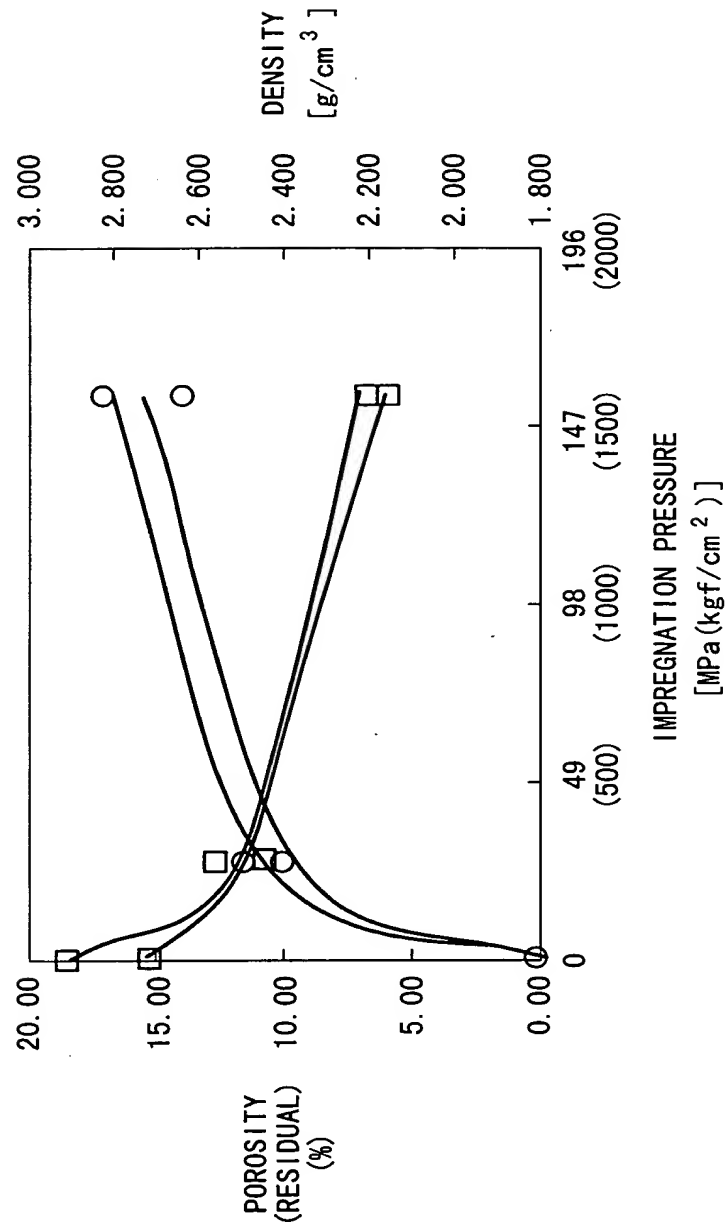
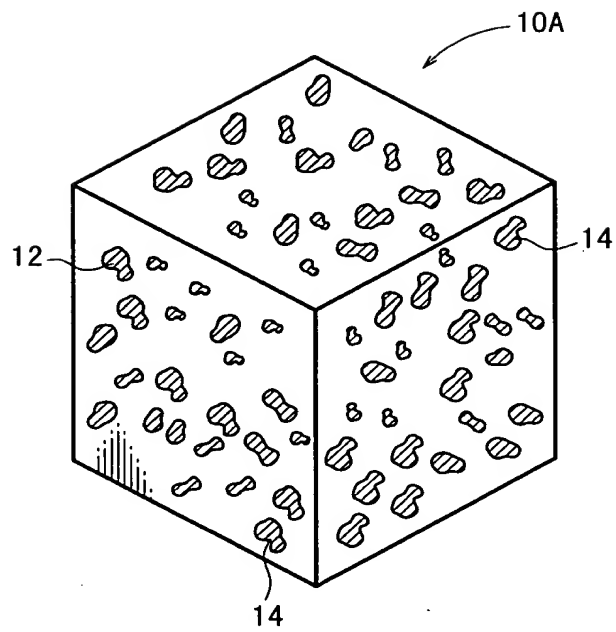


FIG. 1



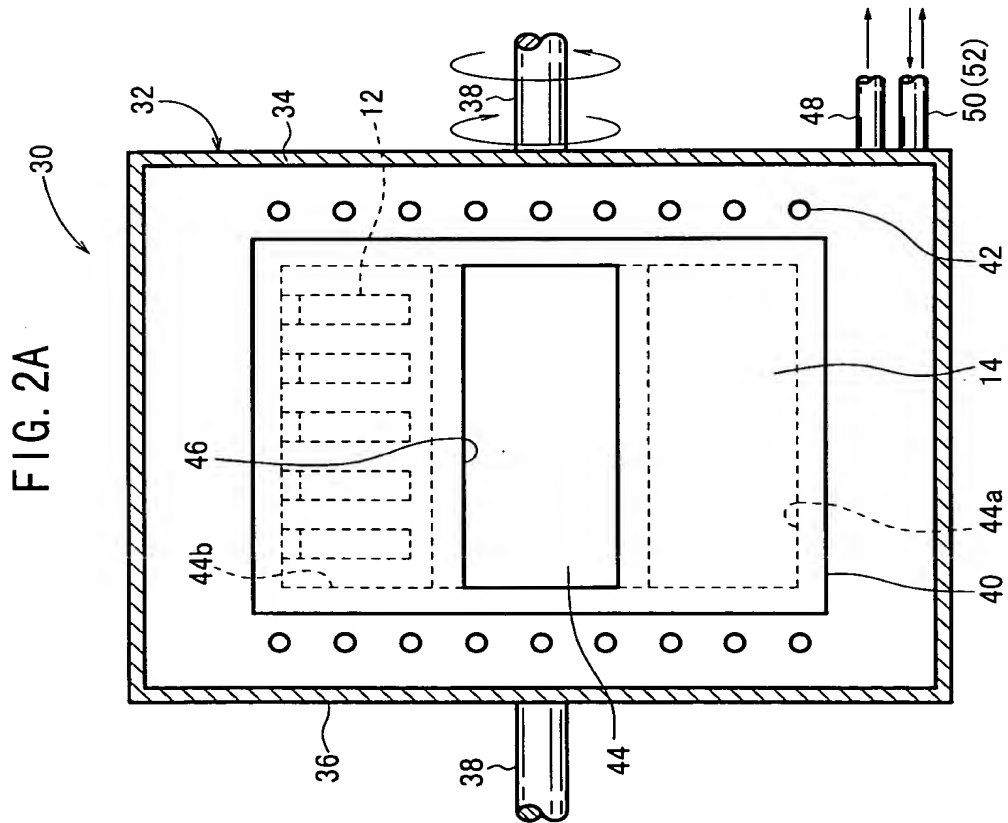
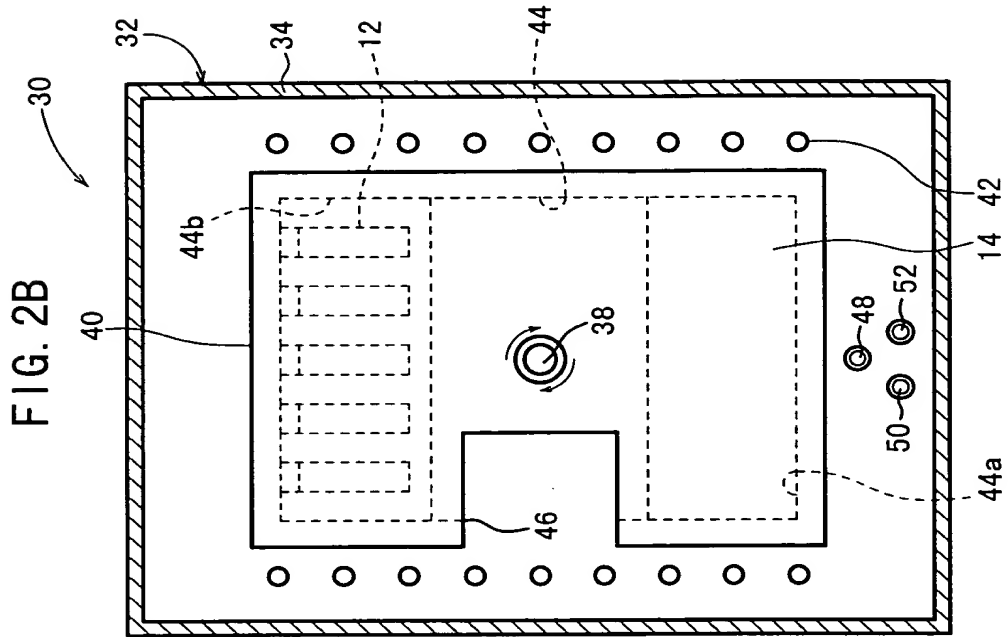


FIG. 3

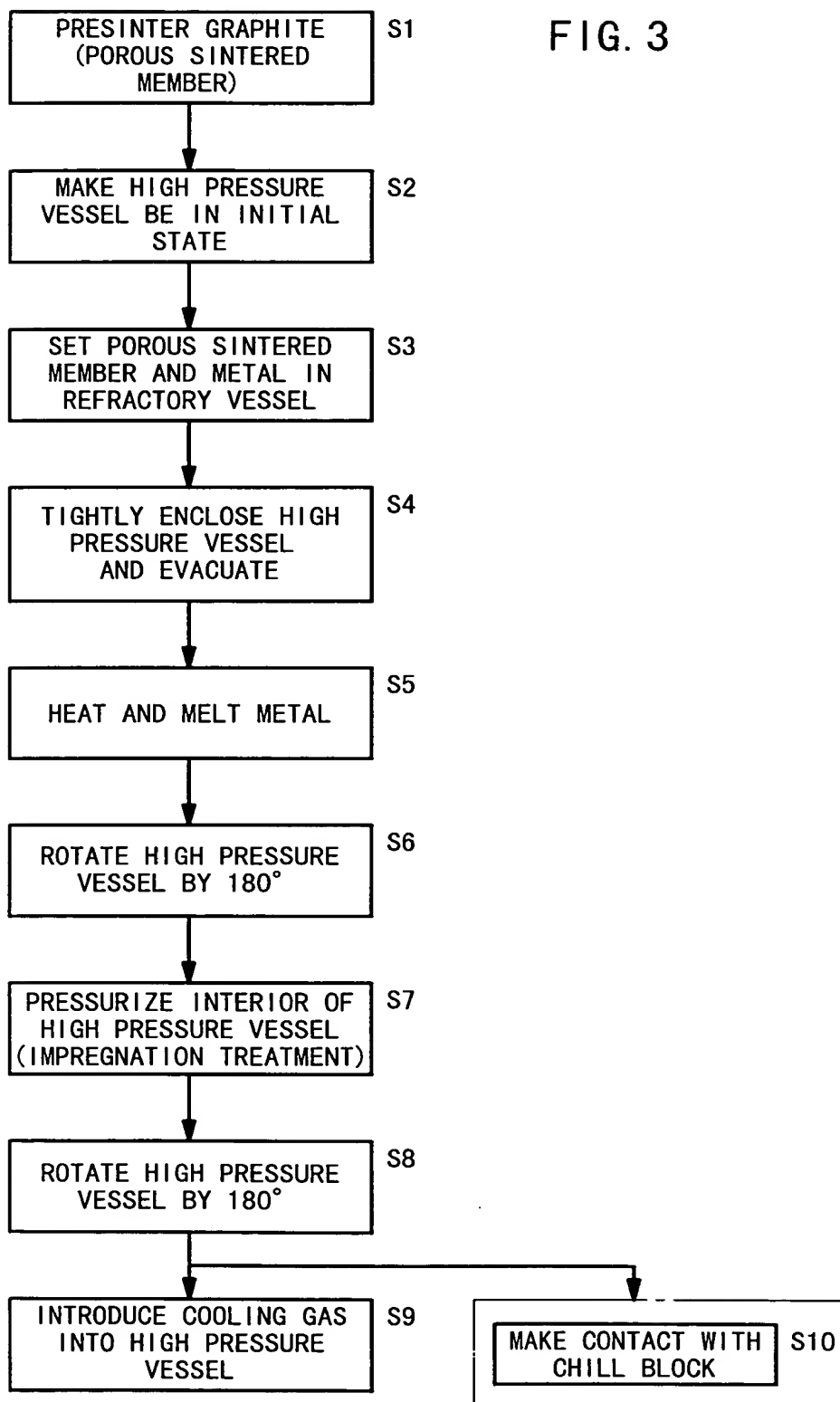


FIG. 4

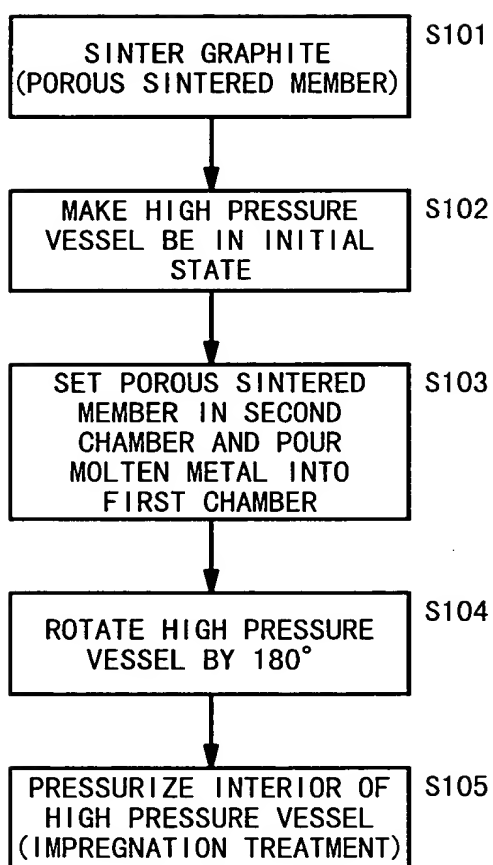


FIG. 5

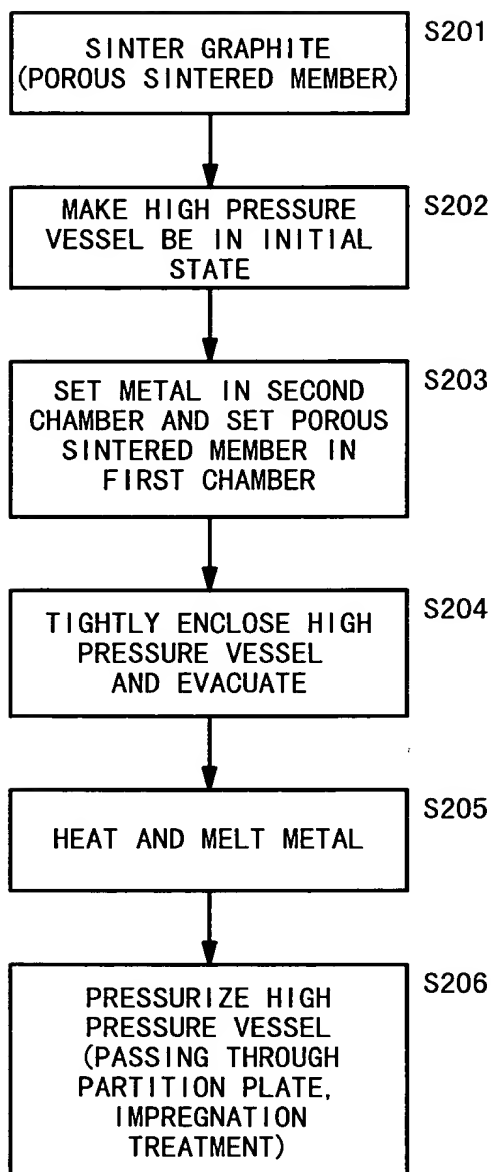


FIG. 6

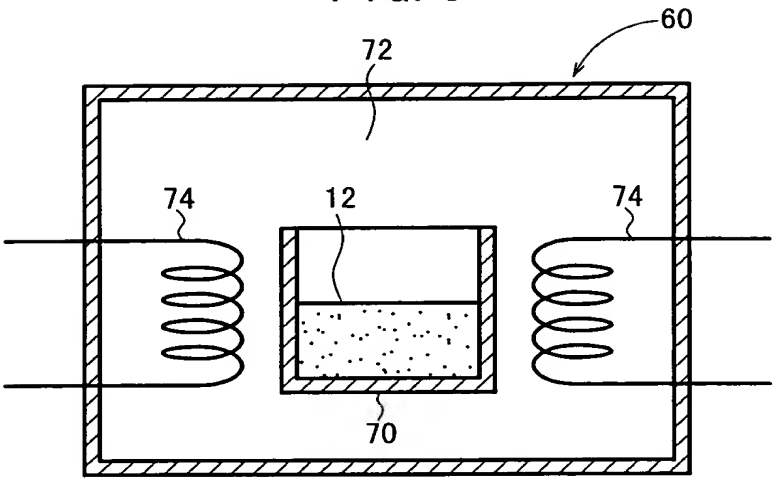


FIG. 7

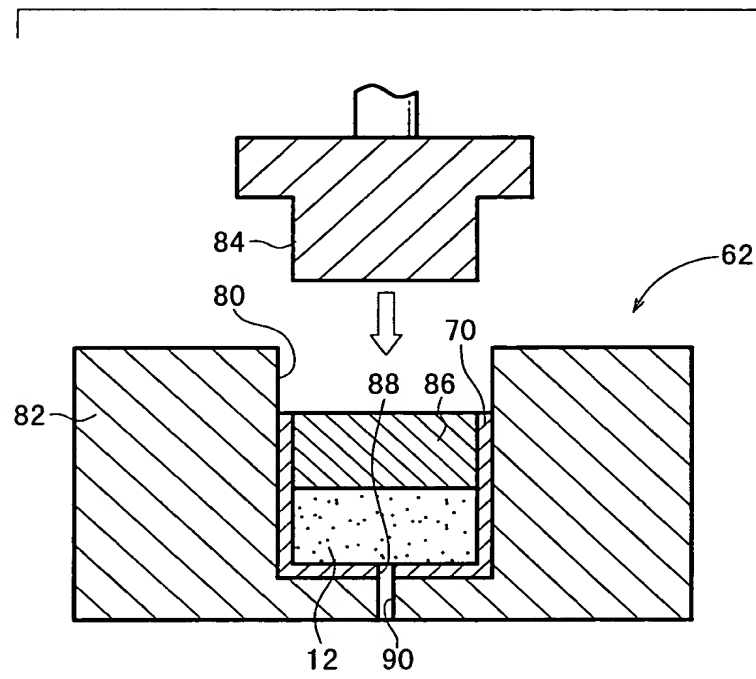


FIG. 8

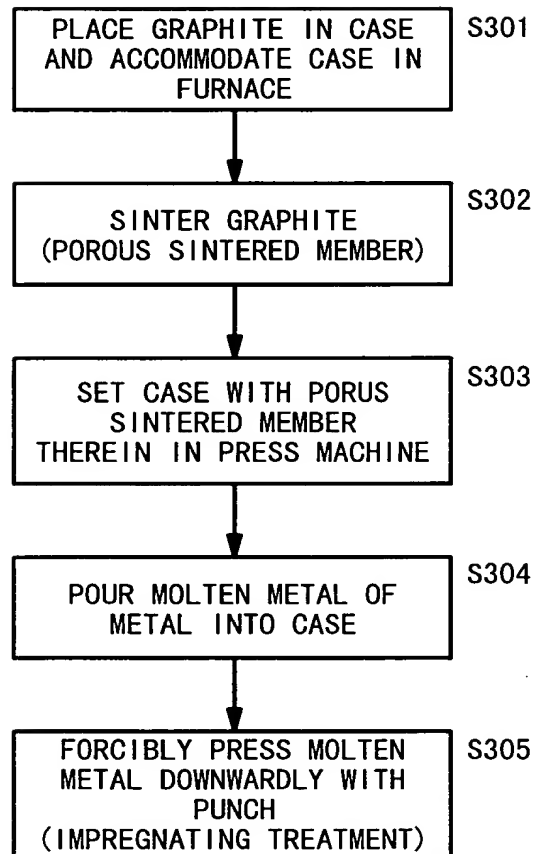


FIG. 9

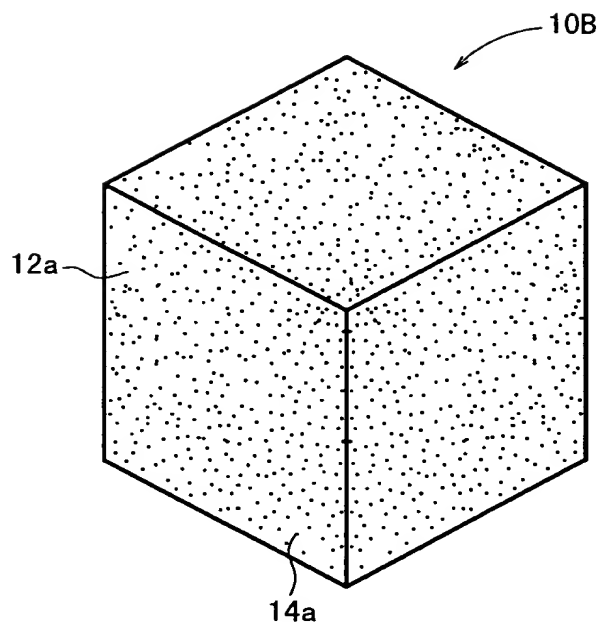


FIG. 10

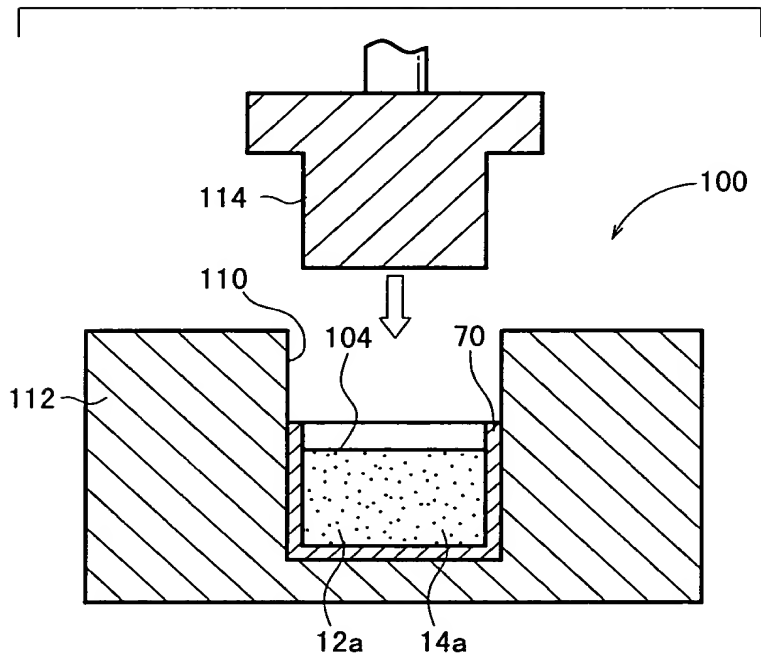
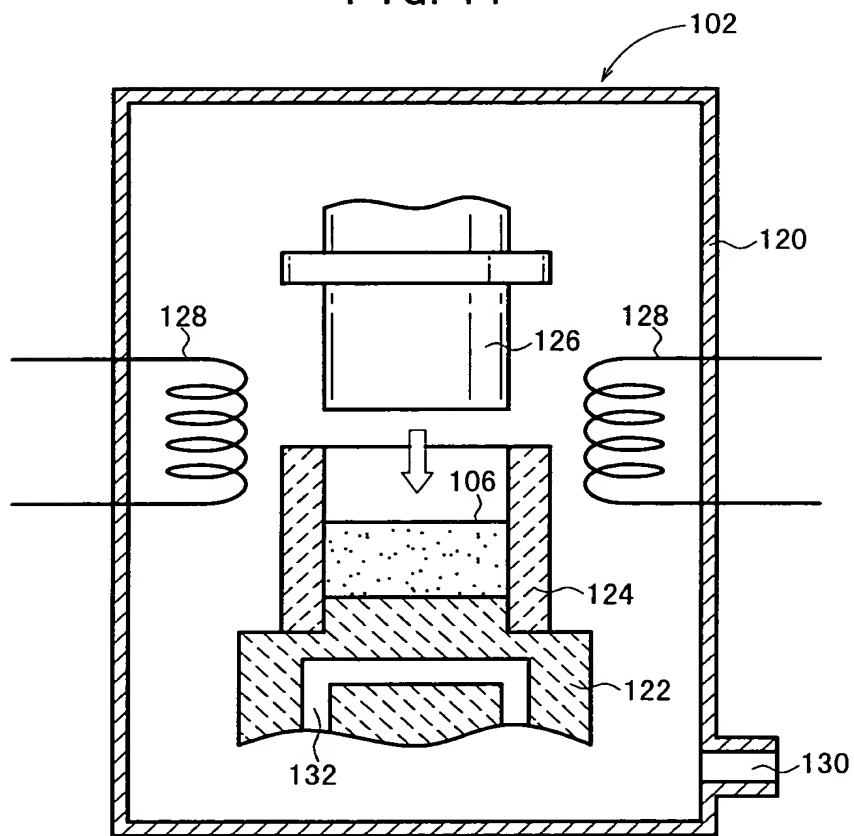


FIG. 11



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FIG. 12

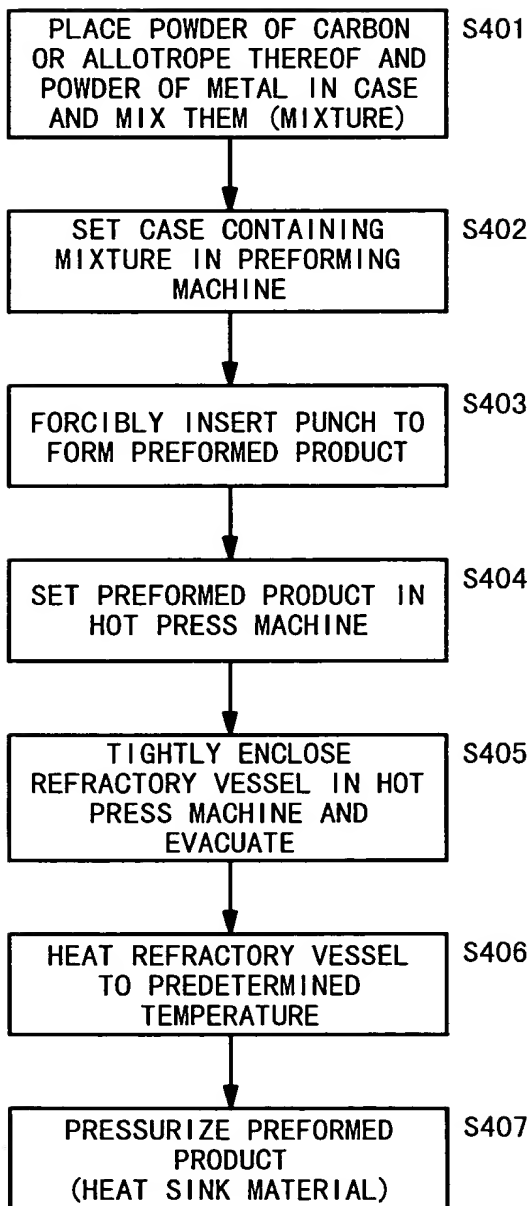


FIG. 13

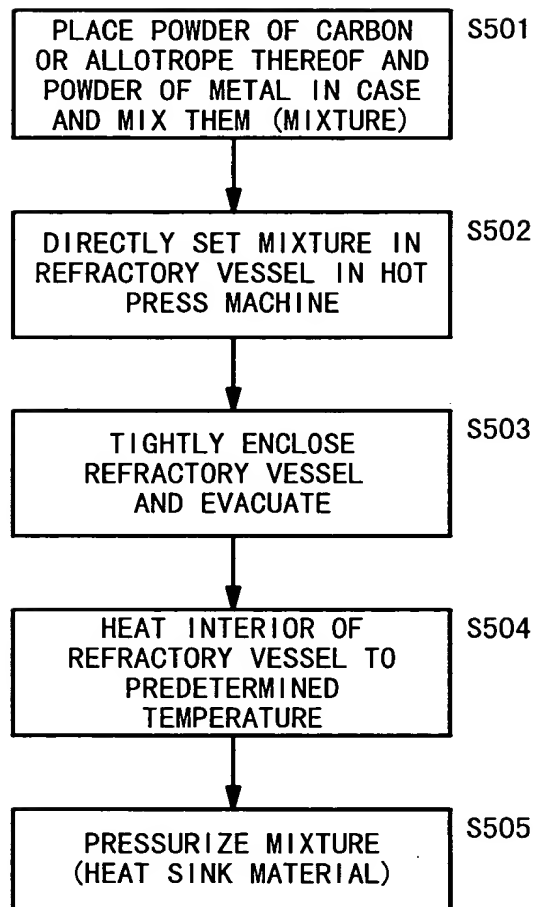


FIG. 14

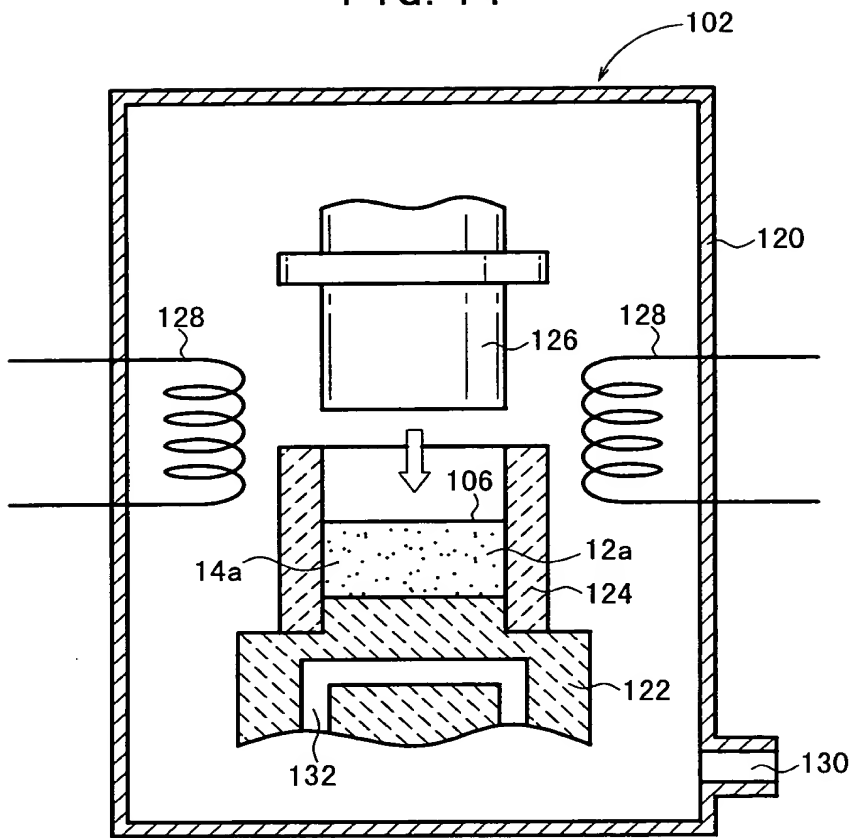


FIG. 15

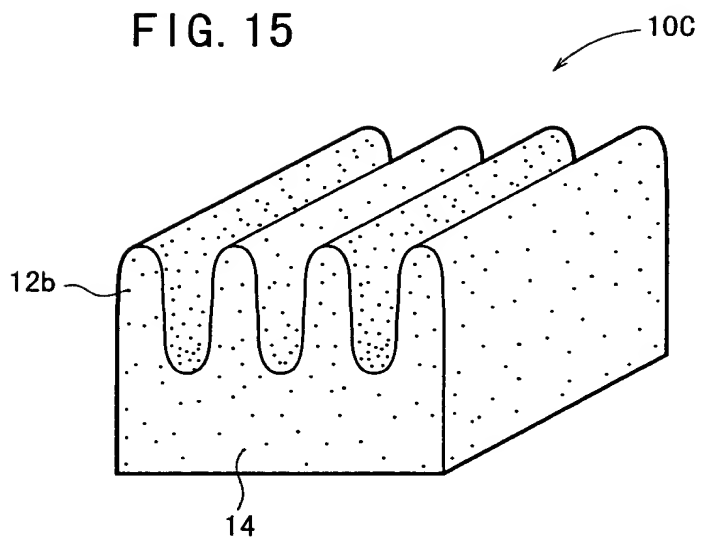
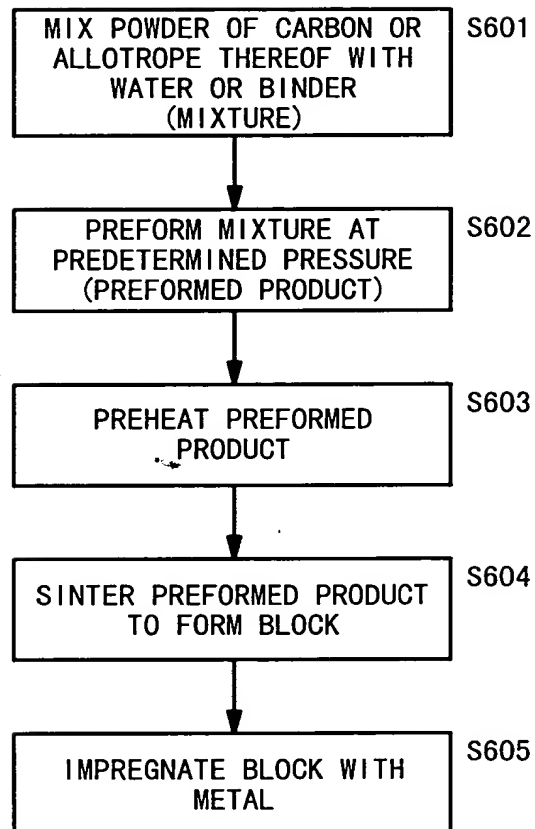


FIG. 16



WATER RESISTANCE

METAL ADDED ELEMENT

SAMPLE	SIZE (mm)	TYPE OF POWDER	PARTICLE SIZE OF POWDER (μ m)	FILLING METHOD			AMOUNT OF ADDITION (wt%)	IMPREG- NATION METHOD	IMPREG- NATION PRESSURE (MPa)	COEFFICIENT OF THERMAL CONDUCTIVITY (W/mK)	COEFFICIENT OF THERMAL EXPANSION ($\times 10^{-6}$ /K)	EFFECT
PW-1	30 \times 120 \times 190	type -P	AVERAGE 120	NO PRESSUR- IZATION	Cu	Nb	0.001	PRESS	60.0	321	14.0	GENERA- TION OF CARBIDE Δ
PW-2	30 \times 120 \times 191	type -S	AVERAGE 50	NO PRESSUR- IZATION	Cu	Nb	0.001	PRESS	60.0	325	13.5	GENERA- TION OF CARBIDE Δ
PW-3	30 \times 120 \times 192	type -R	212- 1180	NO PRESSUR- IZATION	Cu	Nb	0.001	PRESS	60.0	305	13.6	GENERA- TION OF CARBIDE Δ
PW-4	30 \times 120 \times 193	type -P	AVERAGE 120	NO PRESSUR- IZATION	Cu	Nb	0.001	PRESS	60.0	321	14.0	GENERA- TION OF CARBIDE Δ
PW-5	30 \times 120 \times 194	type -P	AVERAGE 120	PRESSUR- IZATION, 7MPa	Cu	Nb	0.001	PRESS	60.0	311	11.5	GENERA- TION OF CARBIDE Δ
PW-6	30 \times 120 \times 195	type -P	AVERAGE 120	PRESSUR- IZATION, 25MPa	Cu	Nb	1.001	PRESS	60.0	301	9.5	GENERA- TION OF CARBIDE Δ

FIG. 18

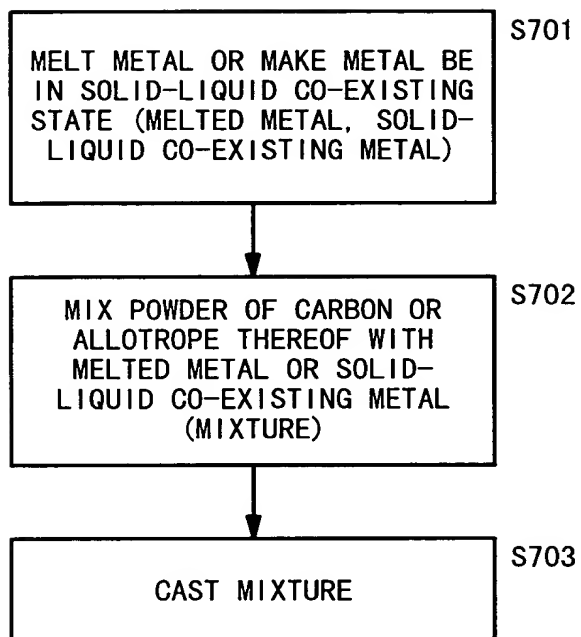


FIG. 19

SAMPLE	SIZE (mm)	METAL	ELEMENT	AMOUNT OF ADDITION (wt%)	IMPREG- NATING METHOD	COEFFICIENT OF THERMAL CONDUCTIVITY (W/mK)		COEFFICIENT OF THERMAL EXPANSION ($\times 10^{-6}/^{\circ}\text{C}$)		BENDING STRENGTH (MPa)		WATER RESISTANCE	EFFECT
						SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS		
p1-1	20x60x60	Al	NONE	NONE	PRESS	171	171	5.3	5.5	33.3	53.9	Δ	NONE
p1-2	20x60x60	Cu	NONE	NONE	PRESS	162	170	5.1	5.1	27.4	41.2	\odot	NONE
p2-1	20x60x60	Cu	Bi	2	PRESS	168	178	5.0	5.1	28.4	45.1	\odot	WETT- ABILITY
p2-2	20x60x60	Cu	Sb	0.5		178	186	5.0	5.1	27.4	41.2		
p2-3	20x60x60	Cu	Te	0.5		180	189	5.0	5.1	26.5	39.2		
p2-4	20x60x60	Cu	Te	2		172	178	4.9	5.0	25.5	38.2		
p2-5	20x60x60	Cu	Te, Bi	0.5, 0.5		169	176	5.0	5.0	26.5	39.2		
p2-6	20x60x60	Cu	Te, Pb	0.5, 2.0		172	185	5.0	5.0	27.4	41.2		
p3-1	20x60x60	Cu	Be	1	PRESS	184	204	5.0	5.0	34.3	57.8	Δ	GENERATION OF CARBIDE
p3-2	20x60x60	Cu	Cr	0.5		187	192	5.0	5.0	37.2	58.8		
p3-3	20x60x60	Cu	Mn	0.5		175	181	5.0	5.0	34.3	56.8		
p3-4	20x60x60	Cu	Nb	0.05		187	190	5.0	5.0	34.3	56.8		
p3-5	20x60x60	Cu	Zr	0.5		172	174	5.0	5.0	24.5	40.2		
p4-1	20x60x60	Cu	Te, Ni	0.5, 0.5	PRESS	165	177	5.0	5.0	27.4	45.1	\odot	COMBINED ADDITION
p5-1	20x60x60	Cu	NONE	NONE	GAS	170	188	5.0	5.0	27.4	41.2	\odot	NONE
p6-1	10x85x180	Cu	Te	2	GAS	185	196	5.0	5.1	26.5	39.2	\odot	WETT- ABILITY
p6-2	20x60x60	Cu	Te	2		192	204	5.0	5.0	28.4	42.1		

FIG. 20

SAMPLE	SIZE (mm)	METAL ELEMENT	AMOUNT OF ADDITION (wt%)	IMPREG- NATING METHOD	COEFFICIENT OF THERMAL CONDUCTIVITY (W/mK)		COEFFICIENT OF THERMAL EXPANSION ($\times 10^{-6}/^{\circ}\text{C}$)		BENDING STRENGTH (MPa)		WATER RESISTANCE	EFFECT
					SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS		
m1-1	20x60x60	Al	NONE	PRESS	161	187	4.5	5.6	34.3	56.8	Δ	NONE
m1-2	20x60x60	Cu	NONE	PRESS	145	181	4.5	5.1	28.4	42.1	\odot	NONE
m2-1	20x60x60	Cu	0.50	PRESS	168	199	4.5	5.1	26.5	39.2	\odot	WETT- ABILITY
m3-1	20x60x60	Cu	1.00	PRESS	184	213	4.5	5.1	36.3	59.8	Δ	GENERATION OF CARBIDE
m3-2	20x60x60	Cu	0.50		170	193	4.5	5.1	37.2	60.8		
m3-3	20x60x60	Cu	0.50		165	192	4.5	5.1	35.3	57.8		
m3-4	20x120x190	Cu	0.05		162	192	4.5	5.1	35.3	57.8		
m3-5	20x60x60	Cu	0.05		169	207	4.5	5.1	35.3	57.8		
m3-6	20x60x60	Cu	0.50	GAS	158	182	4.5	5.1	32.3	52.9	\odot	NONE
m5-1	20x60x60	Cu	NONE		166	198	4.5	5.1	25.5	38.2		

FIG. 21

SAMPLE	SIZE (mm)	ADDITIVE ELEMENT	AMOUNT OF ADDITION (wt%)	(MPa)	(W/mK)	COEFFICIENT OF THERMAL EXPANSION ($\times 10^{-6}/K$)		BENDING STRENGTH (MPa)		COMPRESSIVE STRENGTH (MPa)		EFFECT			
						SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS				
n1-1	20×60×60	Al	NONE	PRESS	26.7	156	311	5.5	6.0	31.4	51.9	46.1	51.0	△	GENERATION OF CARBIDE
n1-4	20×120×190	Al	NONE	PRESS	60.0	185	350	5.5	6.5					△	
n1-2	20×60×60	Cu	NONE	PRESS	26.7	150	310	3.8	4.5	26.5	39.2			◎	
n1-3	20×120×190	Cu	NONE	PRESS	26.7	147	268	3.9	4.5	26.5	39.2			◎	
n2-1	20×60×60	Cu	Te	PRESS	26.7	190	351	3.8	4.5	26.5	39.2			◎	
n3-1	20×60×60	Cu	Be	PRESS	26.7	183	341	3.8	4.5	38.2	62.7			△	
n3-2	20×120×190	Cu	Be	PRESS	156.1	189	342	4.0	4.6	37.2	61.7			△	
n3-3	20×60×60	Cu	Cr	PRESS	26.7	180	320	3.8	4.5	36.3	59.8			△	
n3-4	20×60×60	Cu	Mn	PRESS	26.7	176	330	3.8	4.5	34.3	55.9	42.1	48.0	△	
n3-5	20×60×60	Cu	Nb	PRESS	156.1	198	336	3.8	4.5	35.3	57.8			△	
n3-6	20×120×190	Cu	Nb	PRESS	26.7	167	309	3.8	4.5	35.3	57.8			△	
n3-7	20×60×60	Cu	Zr	PRESS	26.7	158	312	3.8	4.5	34.3	56.8			△	
n3-8	20×120×190	Cu	Nb	PRESS	43.3	182	352	4.5	3.0			40.2	51.9	△	
n3-9	20×120×190	Cu	Nb	PRESS	60.0	182	363	4.0	3.0			42.1	51.9	△	
n3-10	20×120×190	Cu	Nb	PRESS	60.0	196	359	4.0	2.5			51.0	58.8	△	
n3-11	20×120×190	Cu	Be	PRESS	60.0	186	366	4.5	3.5			57.8	64.7	△	
n3-12	20×120×190	Cu	Ni, Sn	PRESS	60.0	190	343					51.9	51.0	◎	
n3-13	20×120×190	Cu	Ni, Si, P	1.0, 0.23, 0.04		190	353					48.0	51.9	○	
n3-14	20×120×190	Cu	Mn	4.180	PRESS	60.0	181	352				51.0	54.9	△	
n3-15	20×120×190	Cu	Cr	2.870	PRESS	60.0	195	387				48.0	51.9	△	
n3-16	20×120×190	Cu	Zr	4.490	PRESS	60.0	207	367				53.9	63.7	△	
n3-17	20×120×190	Cu	Si	11.300	PRESS	26.7	157	333				53.9	60.8	◎	
n3-18	20×120×190	Cu	Si	10.900	PRESS	60.0	159	316				56.8	68.6	◎	
n3-19	20×120×190	Cu	Si	5.170	PRESS	153.0	165	343				52.9	62.7	◎	
n3-20	20×120×190	Cu	Si	5.300	PRESS	43.3	163	325				54.9	60.8	◎	
n5-1	20×60×60	Cu	NONE		GAS	26.7	170	320	3.8	4.5	26.5	39.2		◎	NONE
n7-1	20×120×190	Al	Be	2.000	PRESS	60.0	177	332	5.0	6.5		57.8	62.7	△	GENERATION OF CARBIDE
n7-2	20×120×190	Al	Si	5.000	PRESS	60.0	169	329	5.0	6.5		50.0	61.7	◎	EXPANSION OF SOLID-LIQUID
n7-3	20×120×190	Al	Si	12.000	PRESS	60.0	181	327	5.0	6.5		56.8	68.6	◎	RANGE

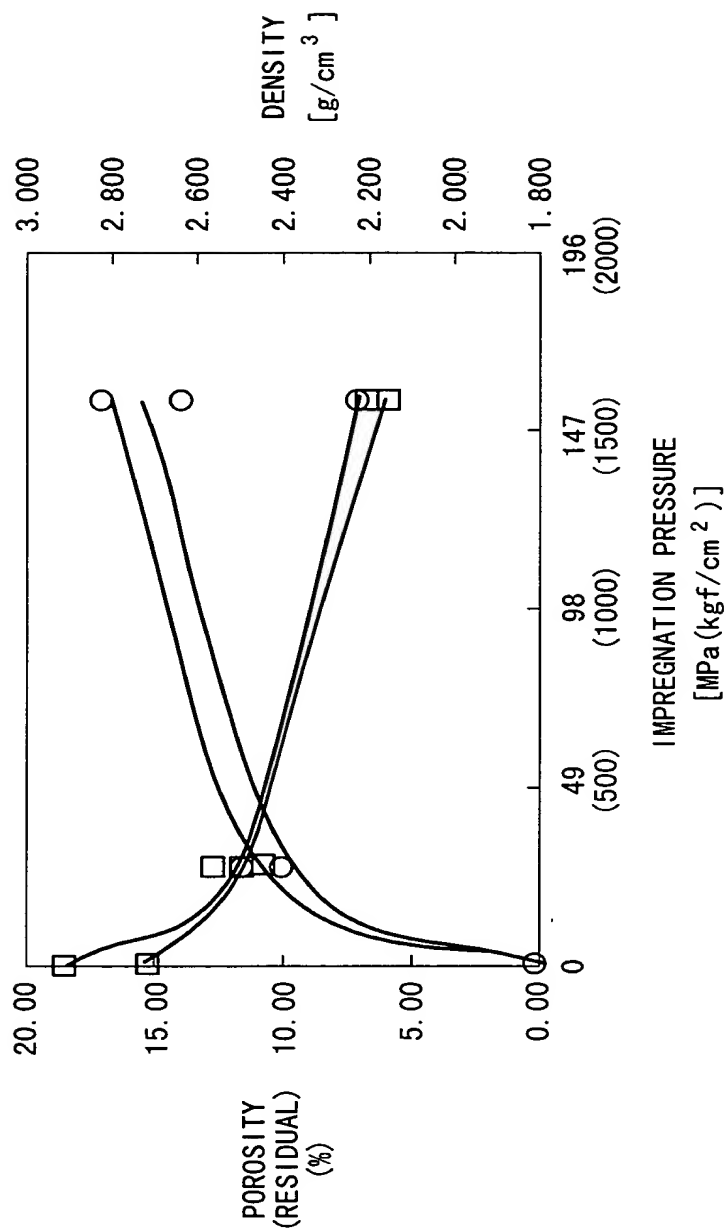
FIG. 22

TYPE OF CARBON	COEFFICIENT OF THERMAL CONDUCTIVITY (W/mK)		COEFFICIENT OF THERMAL EXPANSION ($\times 10^{-6}/^{\circ}\text{C}$)		BENDING STRENGTH (MPa)	
	SURFACE DIRECTION	THICKNESS DIRECTION	SURFACE DIRECTION	THICKNESS DIRECTION	SURFACE DIRECTION	THICKNESS DIRECTION
P	150	160	3.2	3.2	34.3	49.0
M	140	168	3.2	3.2	29.4	44.1
N	150	255	1.8	2.3	14.7	29.4

FIG. 23

SAMPLE	SIZE (mm)	METAL ELEMENT	AMOUNT OF ADDITION (wt%)	IMPREG- NATING METHOD	COEFFICIENT OF THERMAL CONDUCTIVITY (W/mK)		COEFFICIENT OF THERMAL EXPANSION ($\times 10^{-6}/^{\circ}\text{C}$)		BENDING STRENGTH (MPa)		WATER RESISTANCE	EFFECT
					SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS	SUR- FACE	THICK- NESS		
p1-2	20x60x60	Cu	NONE	PRESS	162	170	5.1	5.1	27.4	41.2	☉	NONE
p5-1	20x60x60			GAS	170	188	5.0	5.0	27.4	41.2		
p2-4	20x60x60	Cu	2	PRESS	172	178	4.9	5.0	25.5	38.2	☉	WETT- ABILITY
p6-2	20x60x60		2	GAS	192	204	5.0	5.0	28.4	42.1		
m1-2	20x60x60	Cu	NONE	PRESS	145	181	4.5	5.1	28.4	42.1	☉	NONE
m5-1	20x60x60			GAS	166	198	4.5	5.1	25.5	38.2		
n1-2	20x60x60	Cu	NONE	PRESS	150	310	3.8	4.5	26.5	39.2	☉	NONE
n5-1	20x60x60			GAS	170	320	3.8	4.5	26.5	39.2		

FIG. 24



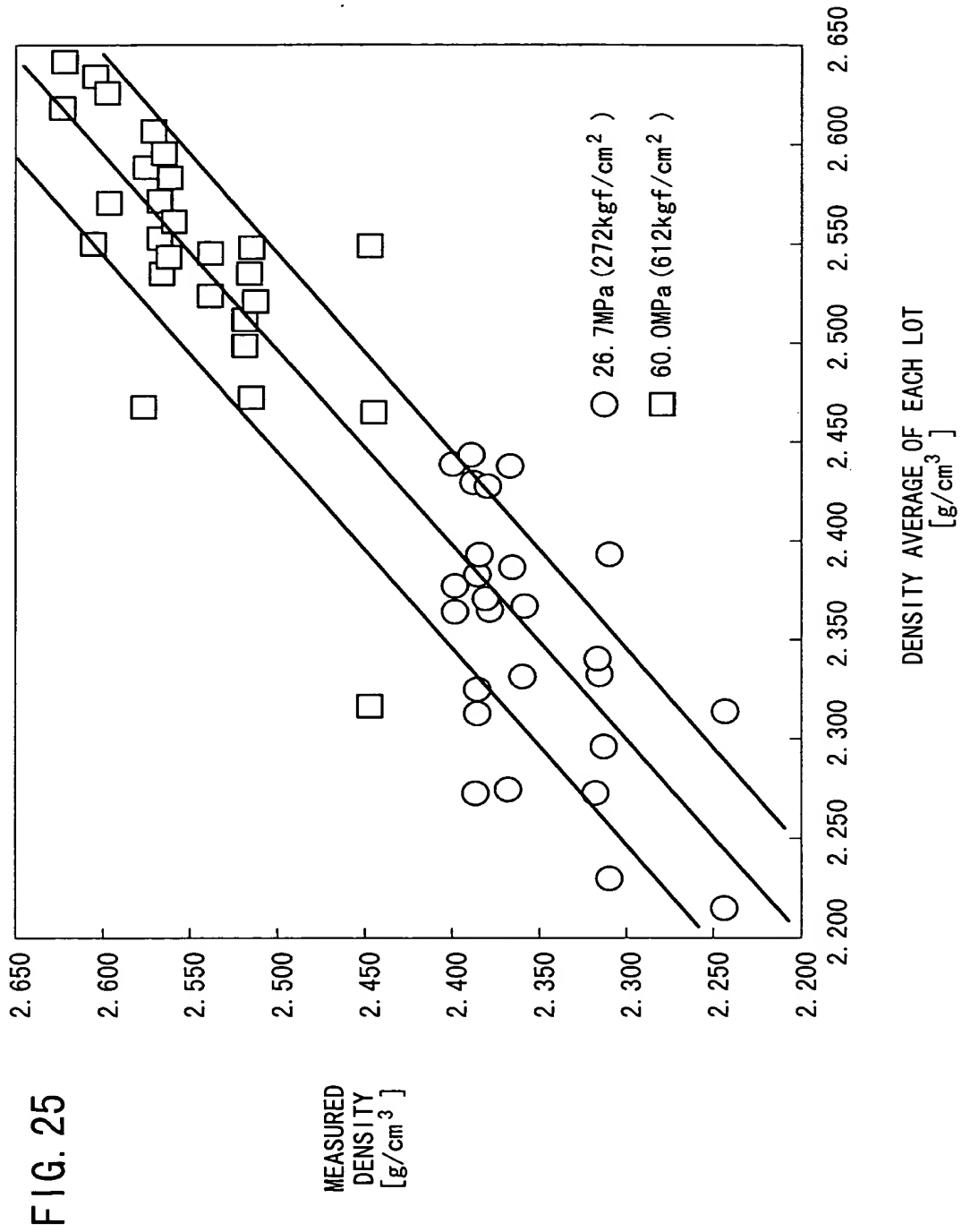
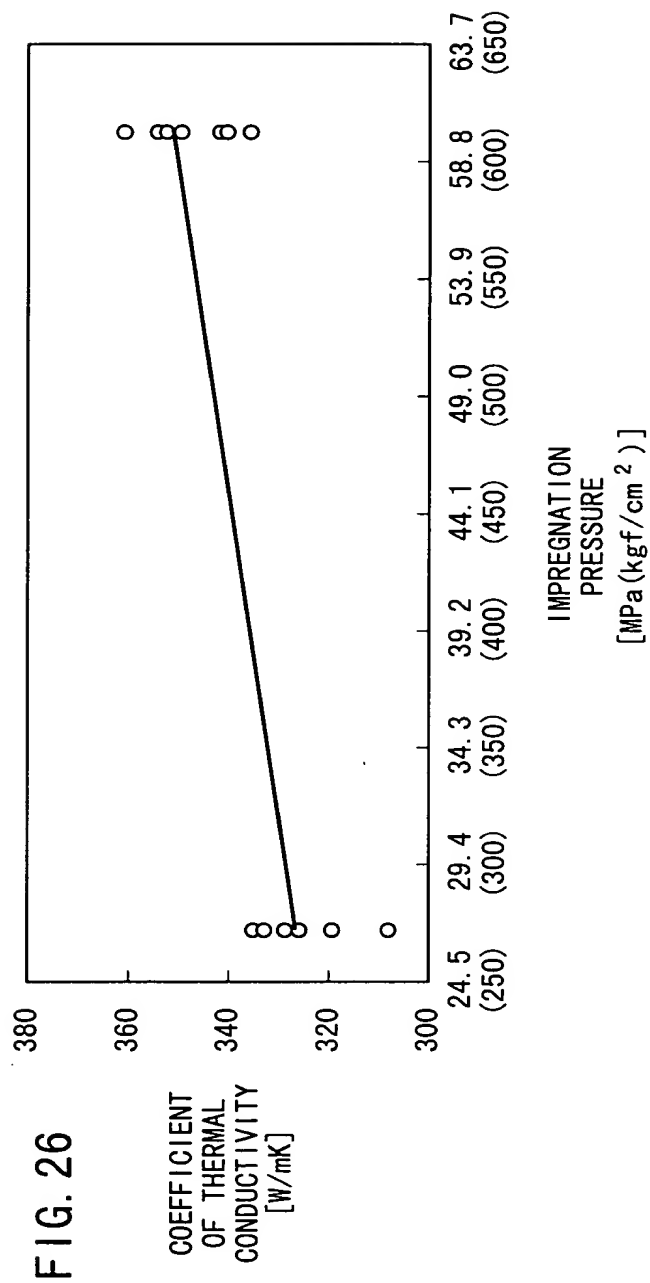
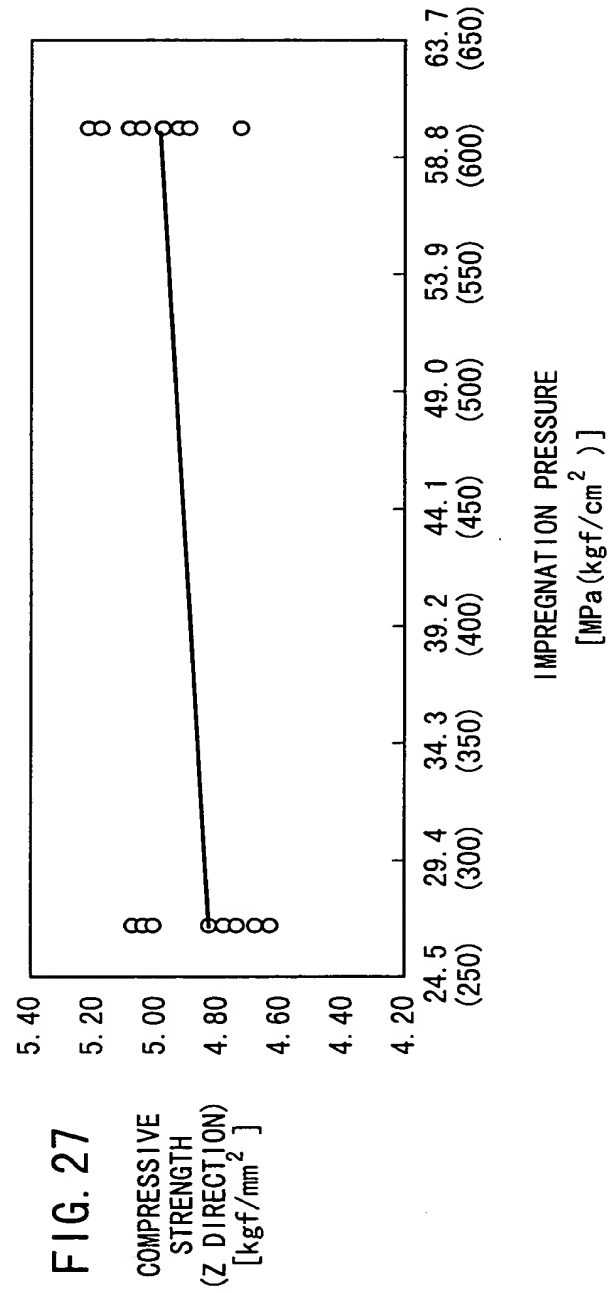
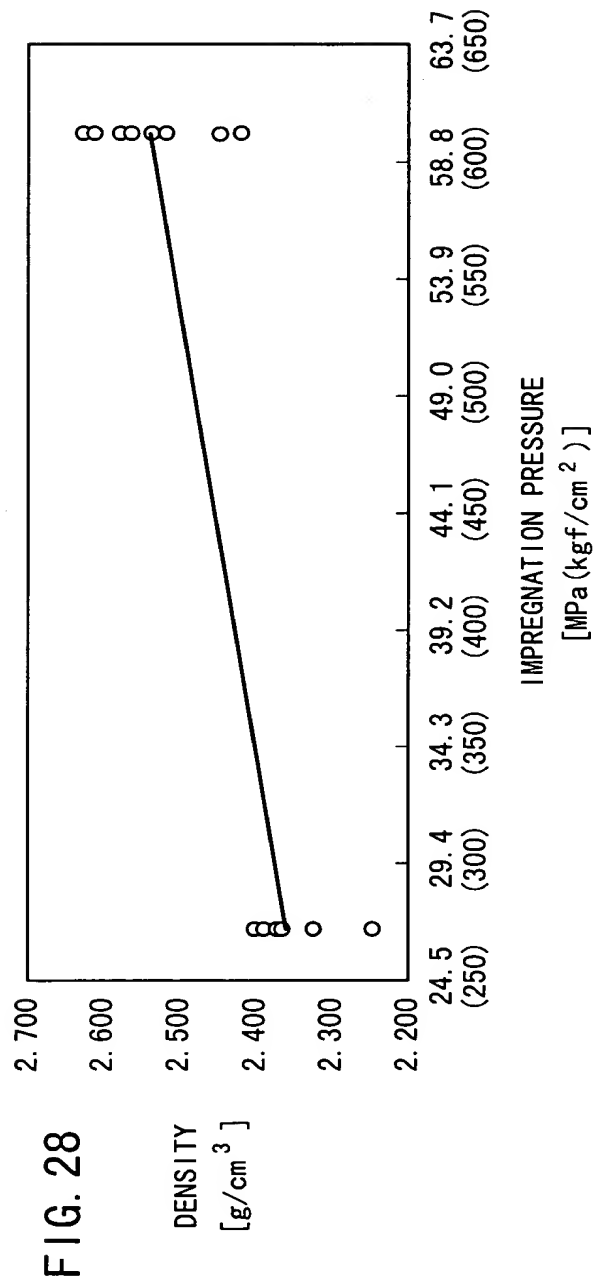


FIG. 25







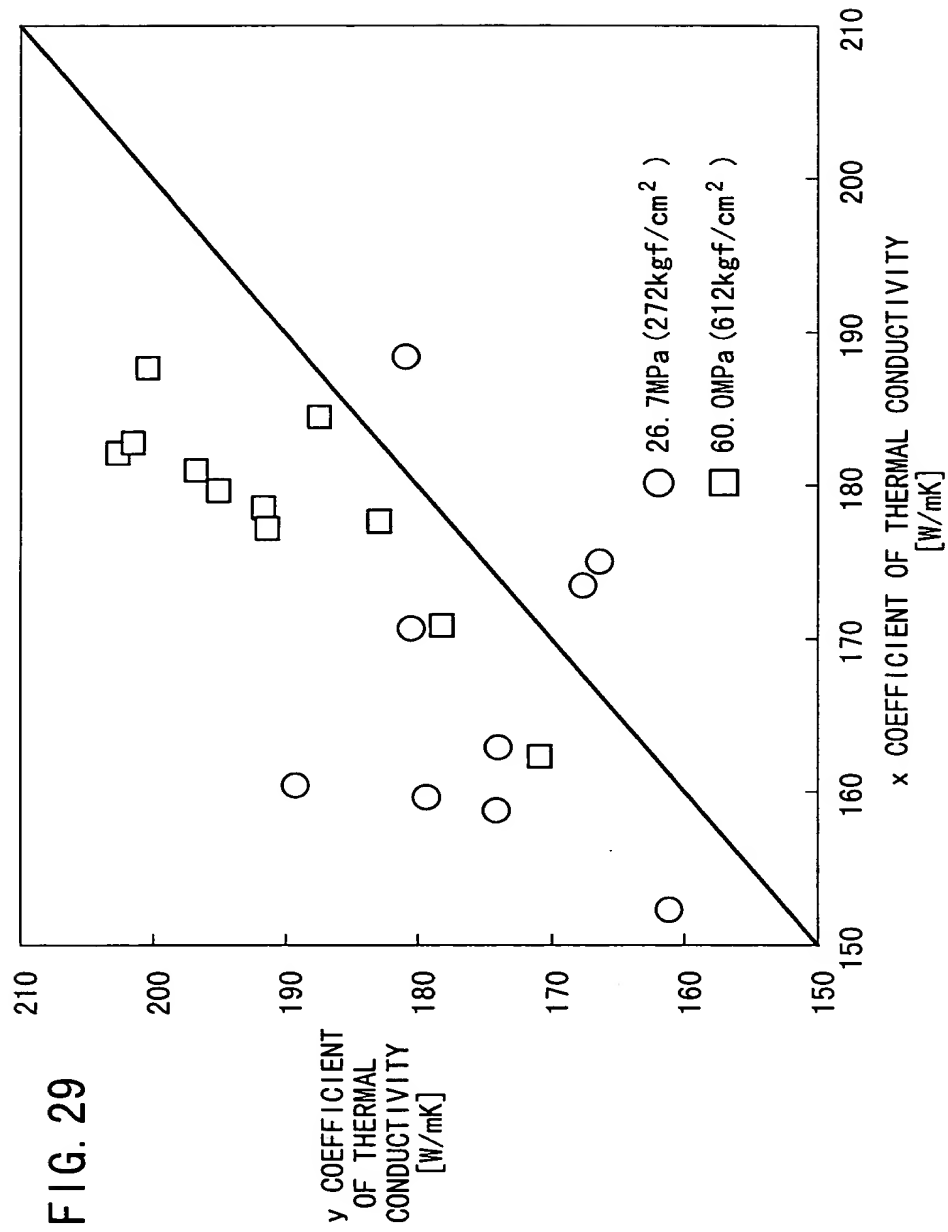
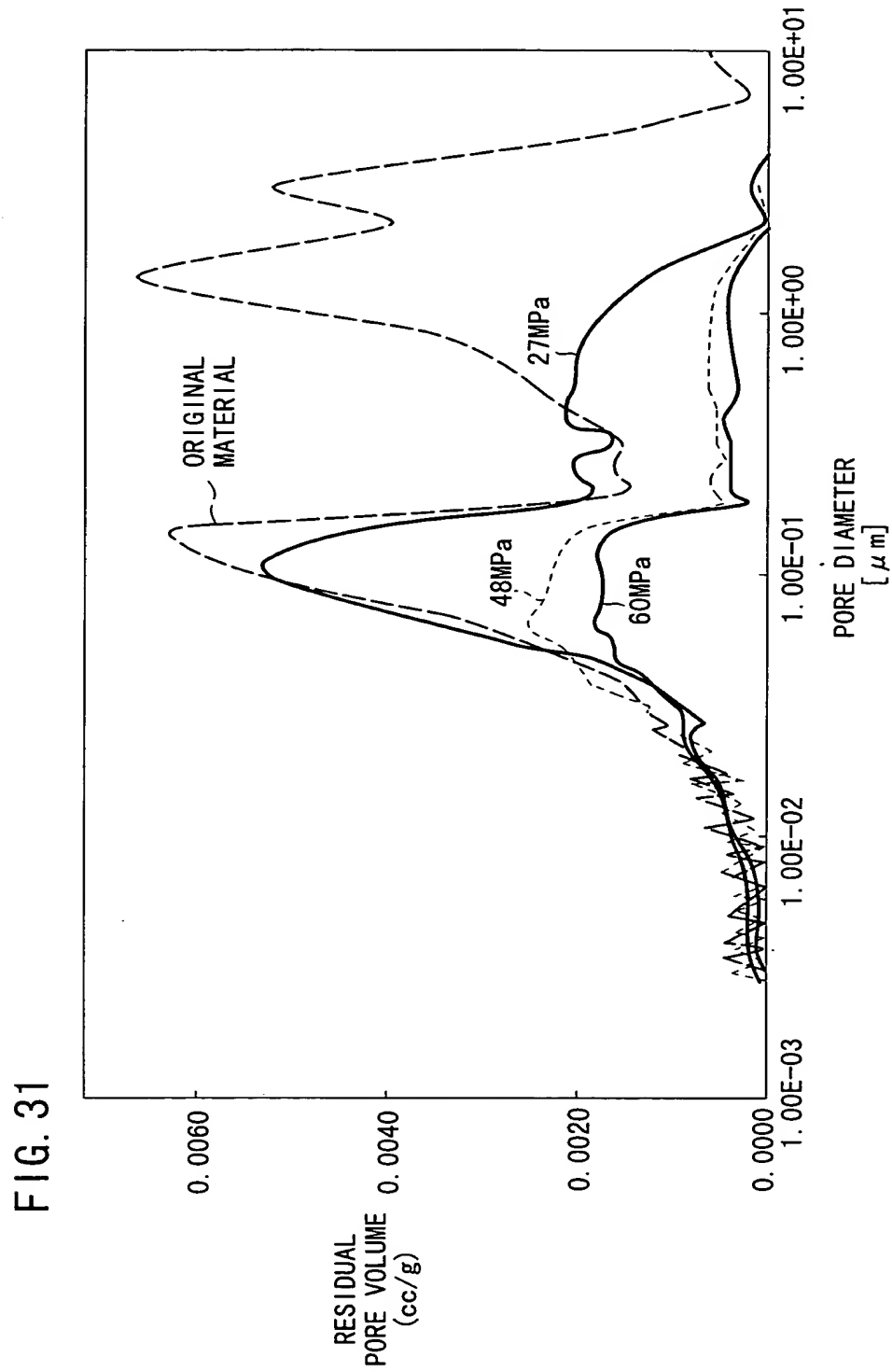


FIG. 30

No.	POROSITY [%]	PORE DIAMETER [μm]	Ni PLATING	Si IMPREG- NATION	IMPREGNATION TEMPERATURE [°C]	PRESSURIZATION [MPa (kgf/cm ²)]	PRESSURIZATION TIME [sec]	COOLING SPEED [°C/min]	REACTION OF Si/Cu	IMPREG- NATION
SAMPLE1	35	70	ABSENT	ABSENT	1130	0.78 (8)	60	260	Δ	Δ
SAMPLE2	44	22	ABSENT	ABSENT	1130	7.84 (80)	20	900	\bigcirc	\bigcirc
SAMPLE3	59	42	ABSENT	PRESENT	1130	11.8 (120)	10	480	\bigcirc	\bigcirc
SAMPLE4	15	5	PRESENT	ABSENT	1130	23.5 (240)	10	900	\bigcirc	\bigcirc
SAMPLE5	59	42	ABSENT	PRESENT	1180	0.78 (8)	60	900	Δ	Δ
SAMPLE6	15	5	ABSENT	ABSENT	1180	3.92 (40)	20	480	\bigcirc	Δ
SAMPLE7	59	42	ABSENT	PRESENT	1180	11.8 (120)	10	900	\bigcirc	\bigcirc
SAMPLE8	44	22	ABSENT	ABSENT	1180	23.5 (240)	10	620	\bigcirc	\bigcirc
SAMPLE9	44	22	ABSENT	PRESENT	1230	0.78 (8)	20	480	\bigcirc	Δ
SAMPLE10	59	42	PRESENT	ABSENT	1230	3.92 (40)	35	790	\bigcirc	\bigcirc
SAMPLE11	35	70	ABSENT	ABSENT	1230	7.84 (80)	100	620	\bigcirc	\bigcirc
SAMPLE12	44	22	ABSENT	PRESENT	1230	23.5 (240)	5	620	\bigcirc	\bigcirc
SAMPLE13	59	42	ABSENT	ABSENT	1280	3.92 (40)	50	790	\bigcirc	\bigcirc
SAMPLE14	35	70	ABSENT	ABSENT	1280	7.84 (80)	35	480	Δ	\bigcirc
SAMPLE15	44	22	PRESENT	ABSENT	1280	7.84 (80)	5	620	\bigcirc	\bigcirc
SAMPLE16	59	42	ABSENT	PRESENT	1280	11.8 (120)	10	790	\bigcirc	\bigcirc
SAMPLE17	20	21	ABSENT	ABSENT	1150	156.1	3	900	\bigcirc	\bigcirc
SAMPLE18	20	19	ABSENT	ABSENT	1150	156.1	5	900	\bigcirc	\bigcirc
SAMPLE19	20	23	ABSENT	ABSENT	1140	69.3	5	900	\bigcirc	\bigcirc
SAMPLE20	20	22	ABSENT	ABSENT	1145	26.7	7	900	\bigcirc	\bigcirc

NOTES REACTION of Si/Cu: \bigcirc NO REACTION \bigcirc SLIGHT REACTION Δ STRONG REACTION
 IMPREGNATION OF Cu : \bigcirc GOOD IMPREGNATION \bigcirc SLIGHTLY INSUFFICIENT IMPREGNATION
 Δ INSUFFICIENT IMPREGNATION



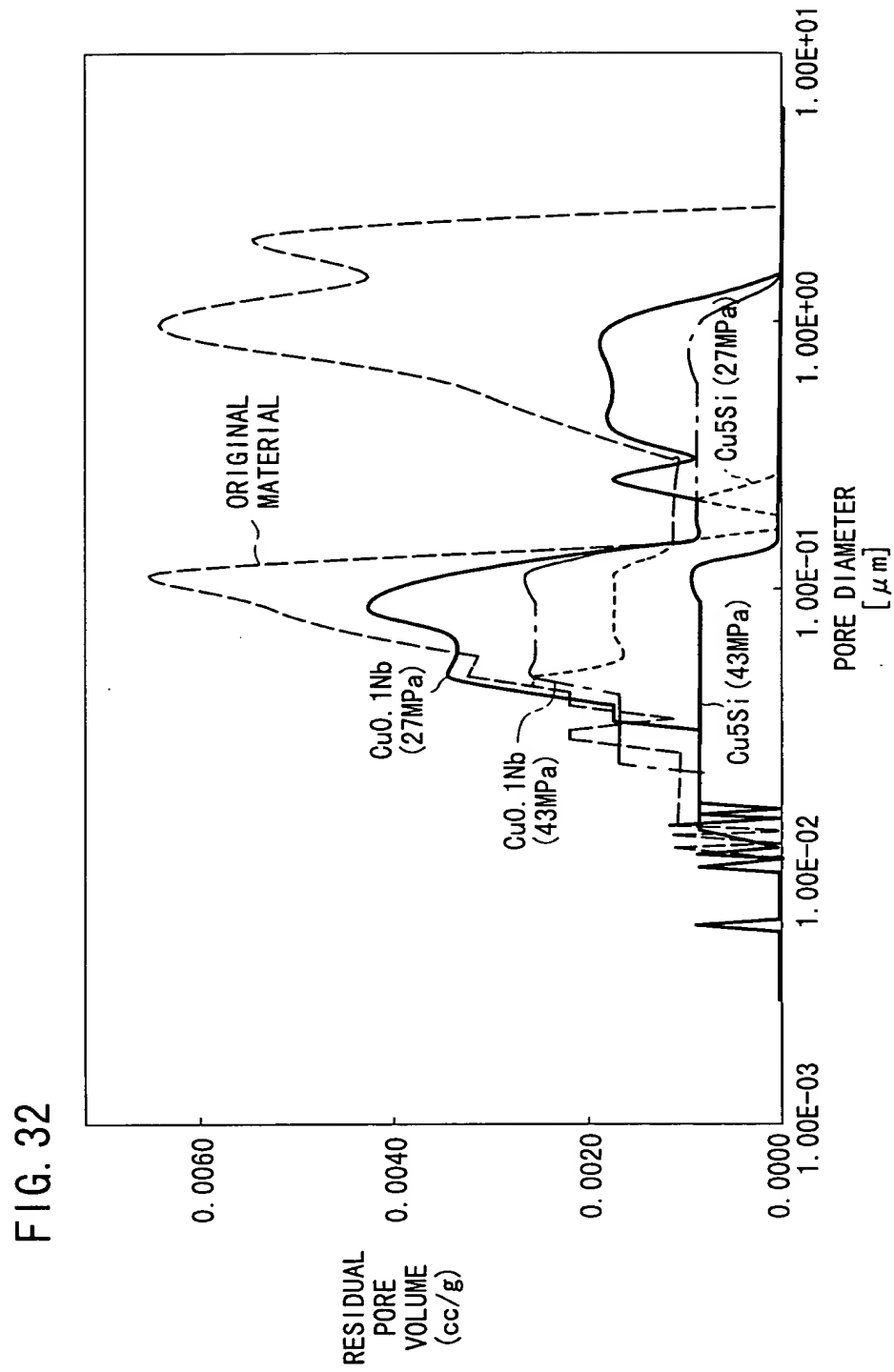


FIG. 33

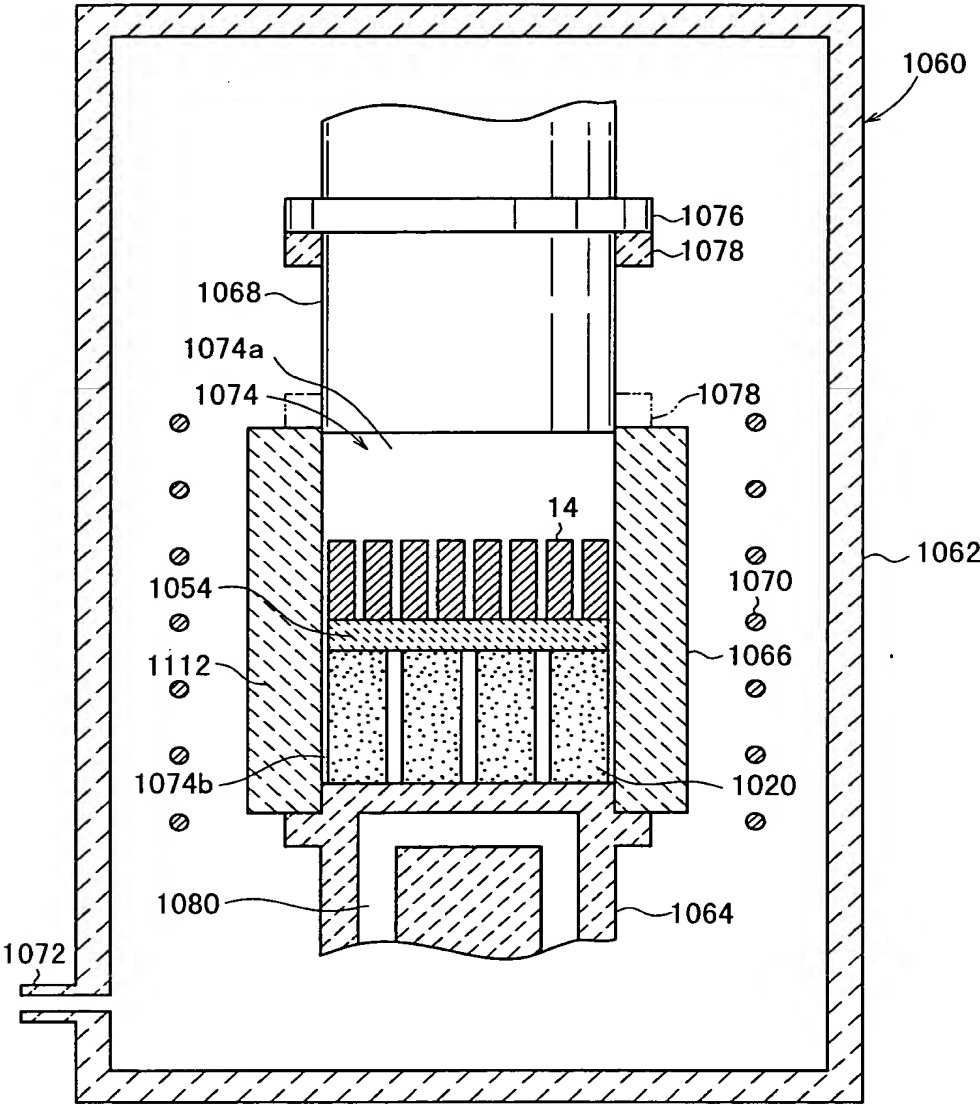


FIG. 34

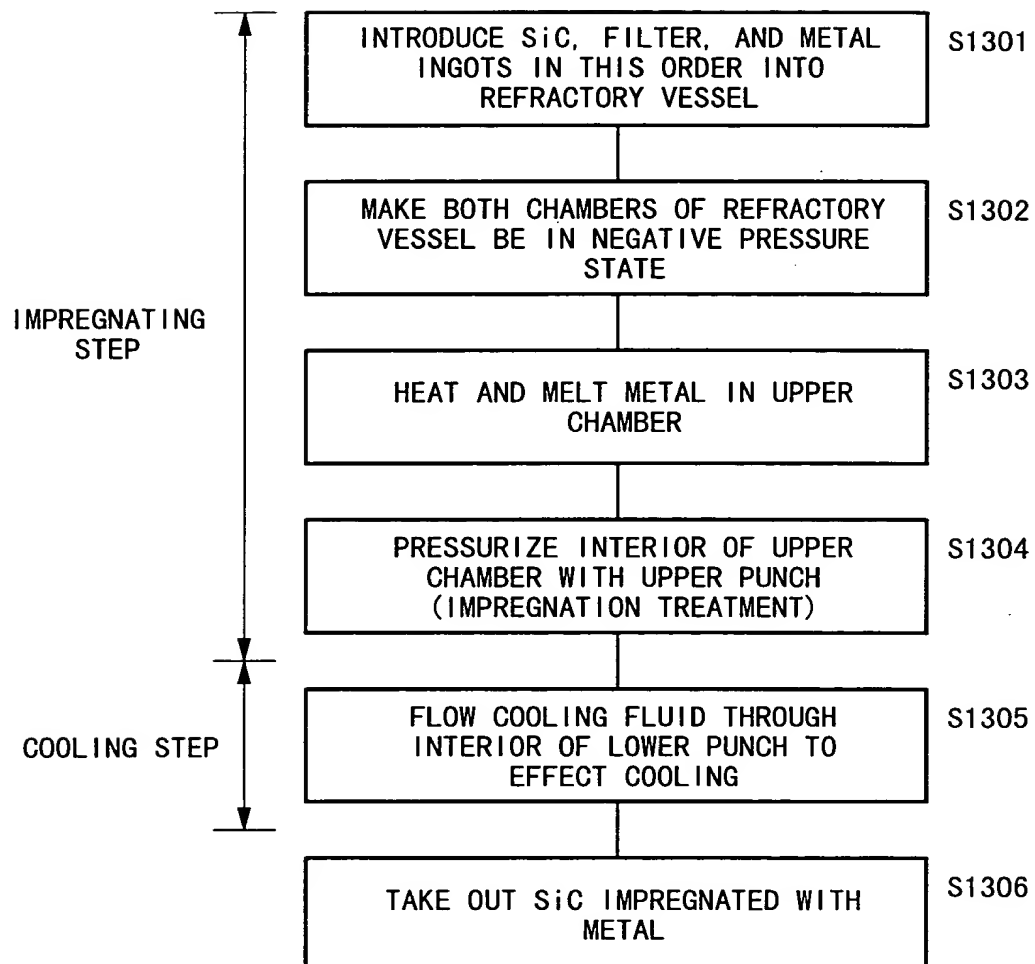


FIG. 35A

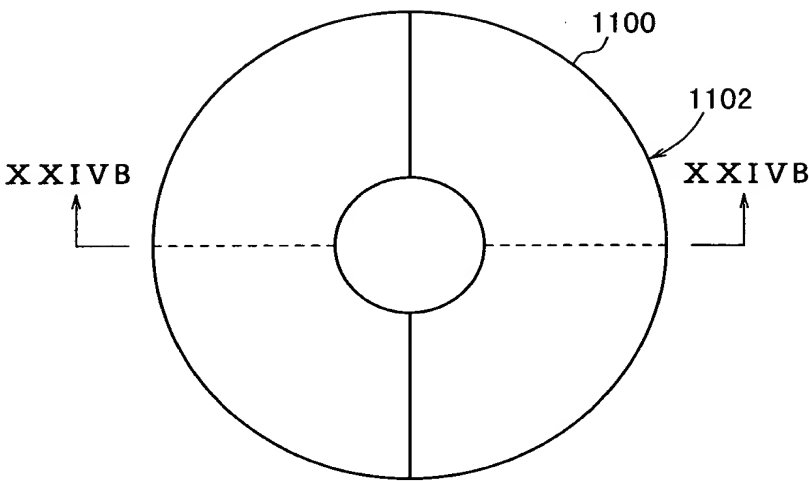


FIG. 35B

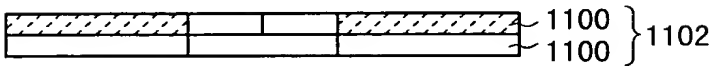
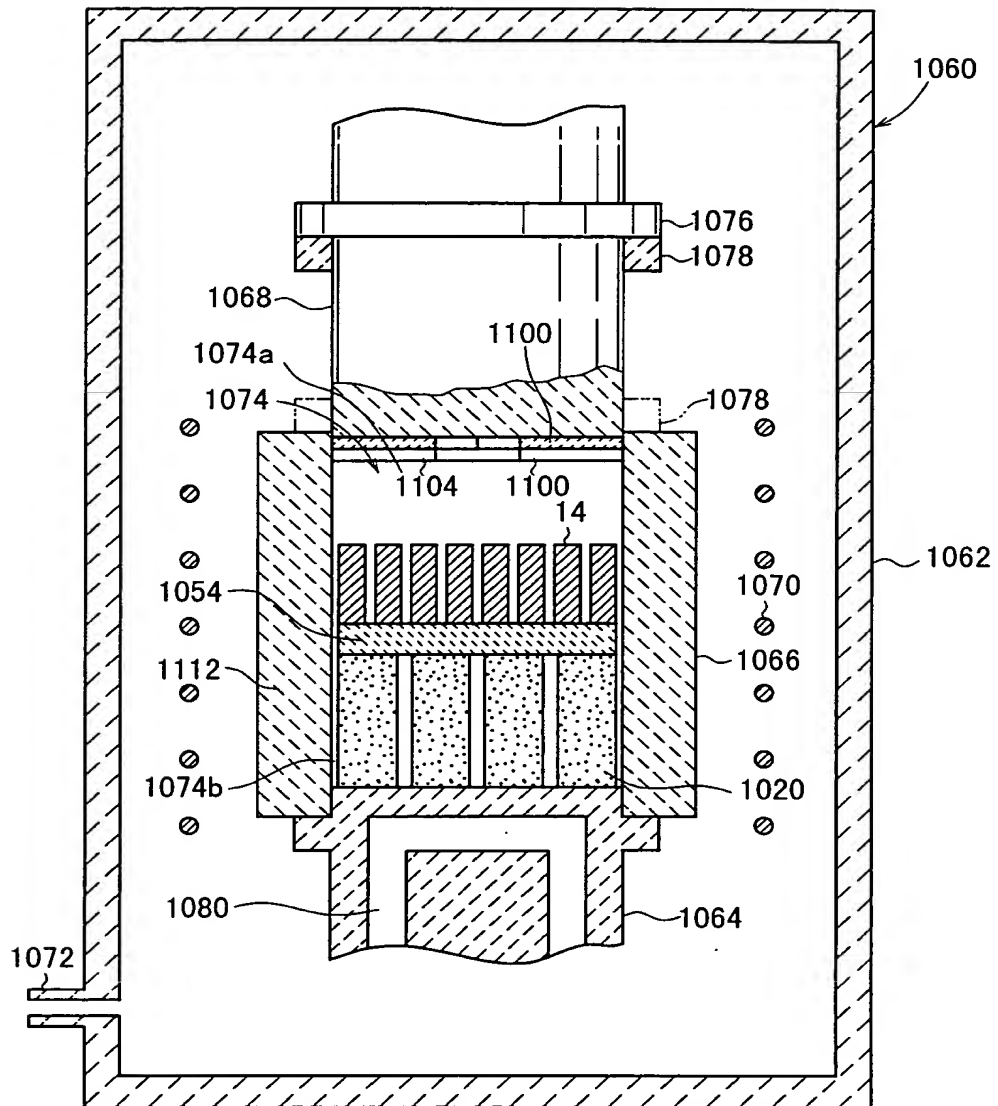


FIG. 36



A detailed cross-sectional view of a semiconductor device assembly 1060. The assembly is housed within a rectangular frame 1062. At the top, a central vertical structure 1068 is capped with a horizontal layer 1076, which is flanked by side layers 1078. Below this, a central cavity 1074a is formed within a block 1074. Inside this cavity, a series of vertical bars 14 are visible. Below the cavity, a layer 1110 is shown, followed by a layer 1112. A central block 1074b is positioned below 1112, containing four vertical columns of a dotted pattern. This block is flanked by side regions 1066. Below 1074b, a layer 1020 is shown, followed by a layer 1080. The entire assembly is supported by a base 1064. On the left side, a small protrusion 1072 is visible. Various hatching patterns are used to distinguish different materials or layers.

FIG. 38

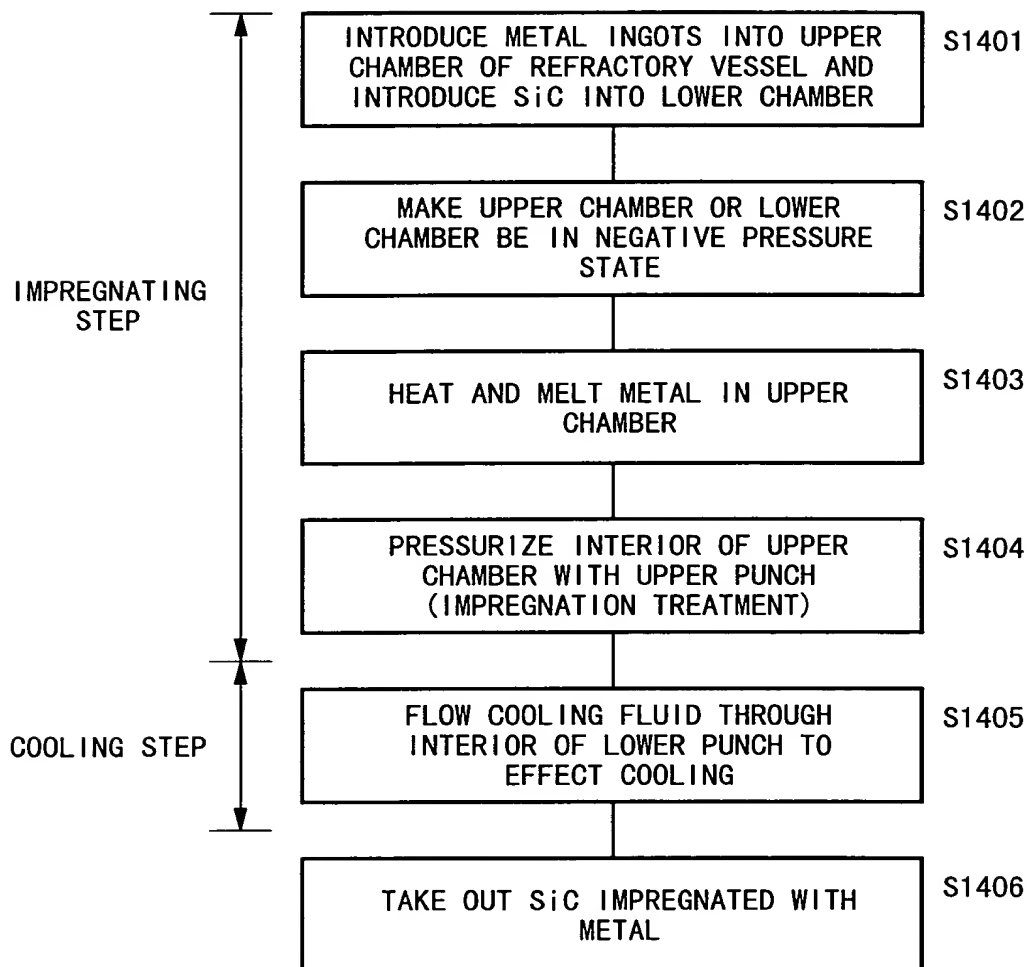


FIG. 39

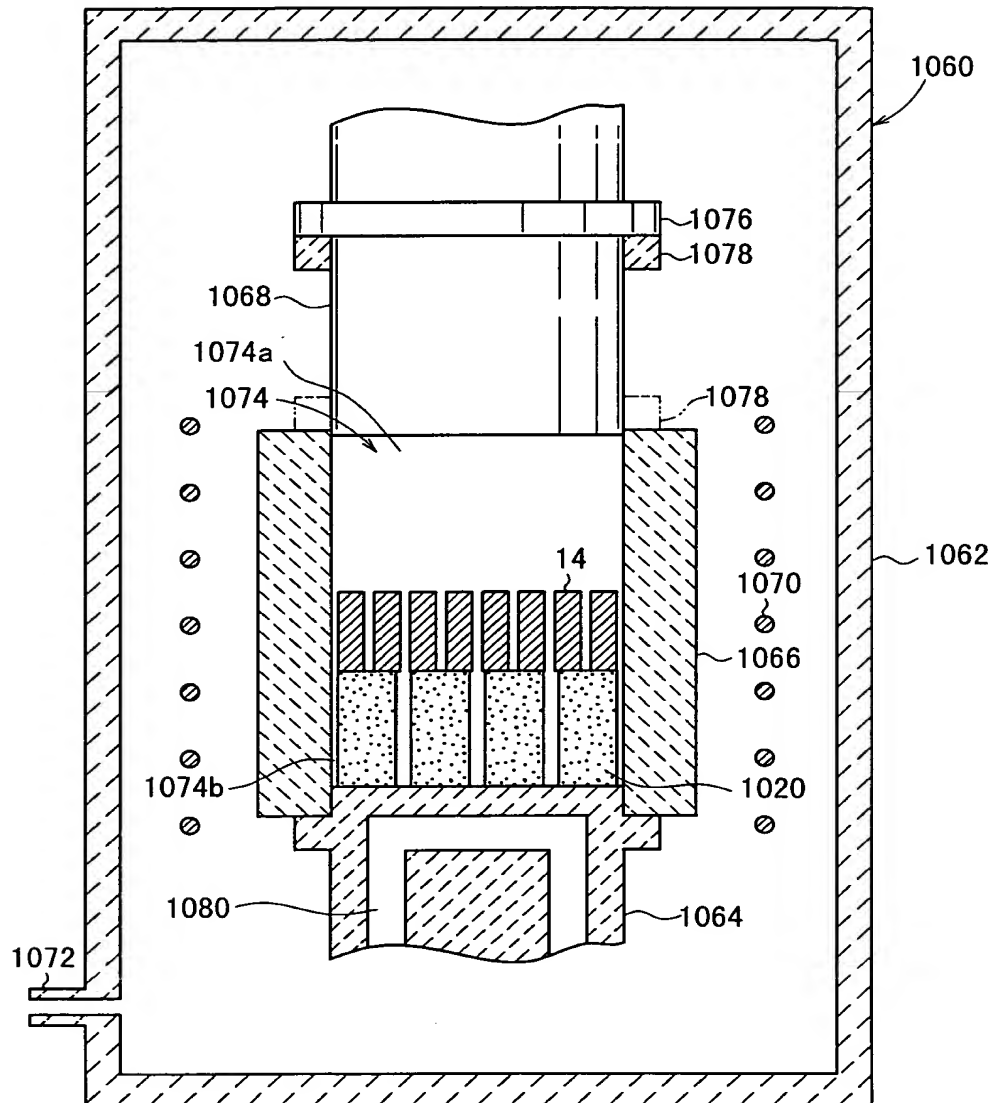


FIG. 40

